

TLP3407S

1. Applications

- Probe Cards
- ATE (Automatic Test Equipment)
- Measuring Instruments
- High-Speed Logic IC Testers
- High-Speed Memory Testers

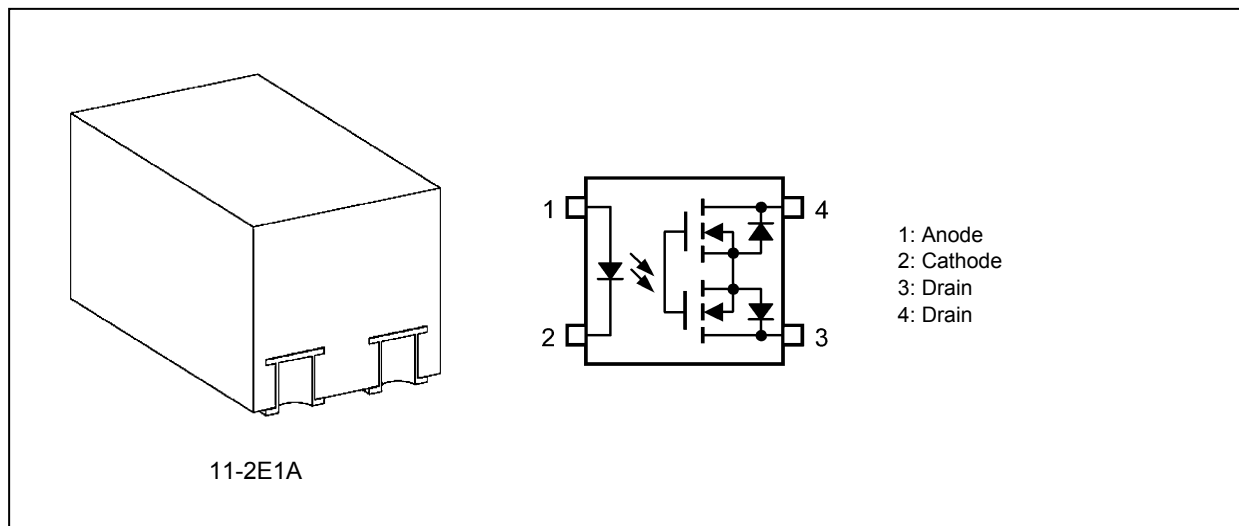
2. General

The TLP3407S photorelay consists of a photo MOSFET optically coupled to an infrared light emitting diode. It is housed in a S-VSON4 package. The TLP3407S features a very small on-resistance and on/off switching of current as high as 1.0 A, making it ideal for switching applications in high-speed testers.

3. Features

- (1) S-VSON4: height = 1.75 mm (max), area = 1.45 mm × 2.0 mm (typ.)
- (2) Normally opened (1-Form-A)
- (3) OFF-state output terminal voltage: 60 V (min)
- (4) Trigger LED current: 3.0 mA (max)
- (5) ON-state current: 1.0 A (max)
- (6) ON-state resistance: 0.3 Ω (max)
- (7) Isolation voltage: 500 Vrms (min)
- (8) Halogen-free

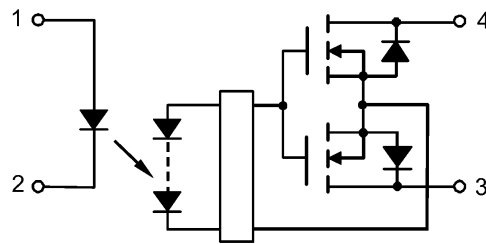
4. Packaging and Pin Assignment



Start of commercial production

2017-02

5. Internal Circuit



6. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Rating	Unit
LED	Input forward current	I _F		30	mA
	Input forward current derating (T _a ≥ 25 °C)	ΔI _F /ΔT _a		-0.3	mA/°C
	Input reverse voltage	V _R		5	V
	Junction temperature	T _j		125	°C
Detector	OFF-state output terminal voltage	V _{OFF}		60	V
	ON-state current	I _{ON}		1.0	A
	ON-state current derating (T _a ≥ 25 °C)	ΔI _{ON} /ΔT _a		-10	mA/°C
	ON-state current (pulsed) (t = 100 ms, Duty = 1/10)	I _{ONP}		3.0	A
	Junction temperature	T _j		125	°C
Common	Storage temperature	T _{stg}		-55 to 125	°C
	Operating temperature	T _{opr}		-40 to 110	
	Lead soldering temperature (10 s)	T _{sol}		260	
	Isolation voltage AC, 60 s, R.H. ≤ 60 %	BV _S	(Note 1)	500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

Note: This device is sensitive to electrostatic discharge (ESD). Extreme ESD conditions should be guarded against by using proper antistatic precautions for the worktable, operator, solder iron, soldering equipment and so on.

7. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
Supply voltage	V _{DD}		—	—	48	V
Input forward current	I _F		5	7.5	20	mA
ON-state current	I _{ON}		—	—	1.0	A
Operating temperature	T _{opr}		-20	—	100	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

8. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V_F		$I_F = 10\text{ mA}$	1.1	1.26	1.4	V
	Input reverse current	I_R		$V_R = 5\text{ V}$	—	—	10	μA
	Input capacitance	C_t		$V = 0\text{ V}, f = 1\text{ MHz}$	—	30	—	pF
Detector	OFF-state current	I_{OFF}		$V_{OFF} = 60\text{ V}$	—	—	1	μA
				$V_{OFF} = 50\text{ V}$	—	—	1	nA
	Output capacitance	C_{OFF}		$V = 0\text{ V}, f = 100\text{ MHz}, t < 1\text{ s}$	—	80	150	pF

9. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Trigger LED current	I_{FT}		$I_{ON} = 100\text{ mA}$	—	0.7	3.0	mA
Return LED current	I_{FC}		$I_{OFF} = 10\text{ }\mu\text{A}$	0.1	—	—	
ON-state resistance	R_{ON}		$I_{ON} = 1\text{ A}, I_F = 5\text{ mA}, t < 1\text{ s}$	—	0.2	0.3	Ω

10. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	$V_S = 0\text{ V}, f = 1\text{ MHz}$	—	0.9	—	pF
Isolation resistance	R_S	(Note 1)	$V_S = 500\text{ V}, R.H. \leq 60\%$	—	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	500	—	—	Vrms
			AC, 1 s in oil	—	1000	—	
			DC, 60 s, in oil	—	1000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

11. Switching Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Turn-on time	t_{ON}		See Fig. 11.1. $R_L = 200\text{ }\Omega, V_{DD} = 20\text{ V}, I_F = 5\text{ mA}$	—	0.75	2.0	ms
Turn-off time	t_{OFF}			—	0.04	0.3	

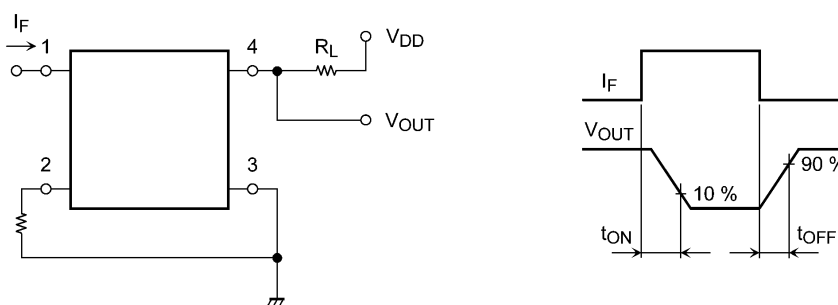


Fig. 11.1 Switching Time Test Circuit and Waveform

12. Characteristics Curves (Note)

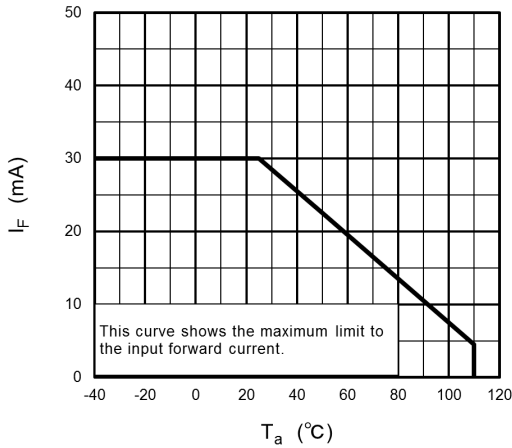


Fig. 12.1 $I_F - T_a$

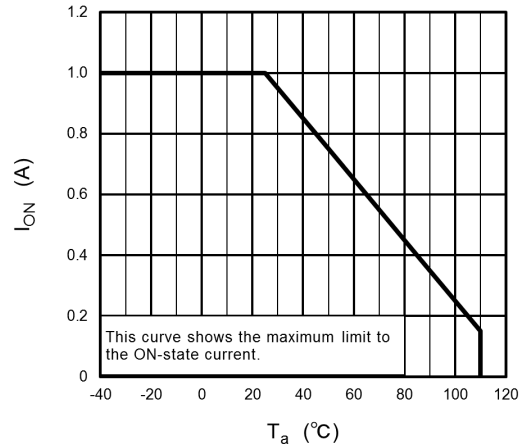


Fig. 12.2 $I_{ON} - T_a$

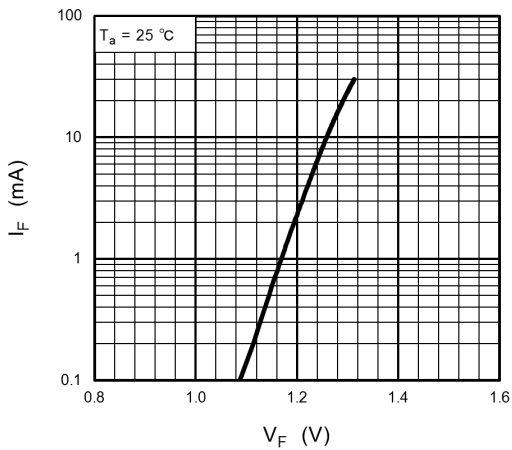


Fig. 12.3 $I_F - V_F$

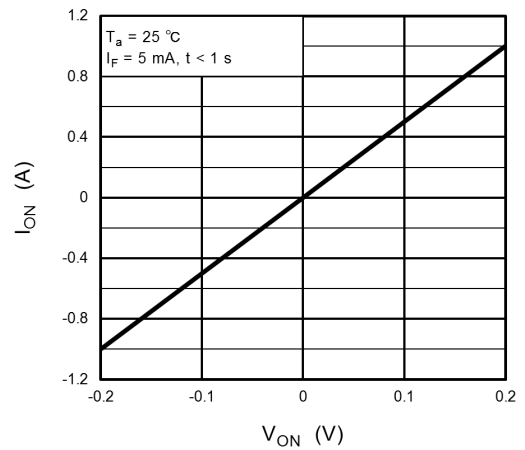


Fig. 12.4 $I_{ON} - V_{ON}$

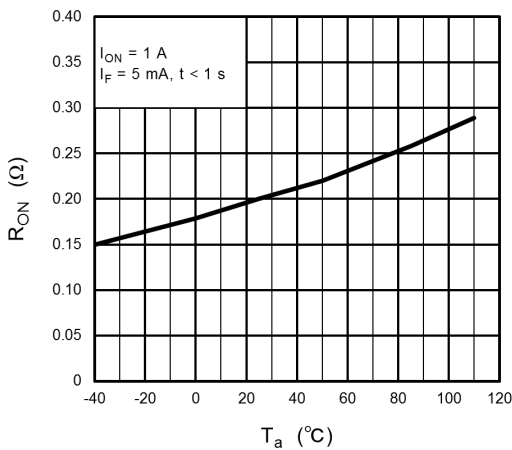


Fig. 12.5 $R_{ON} - T_a$

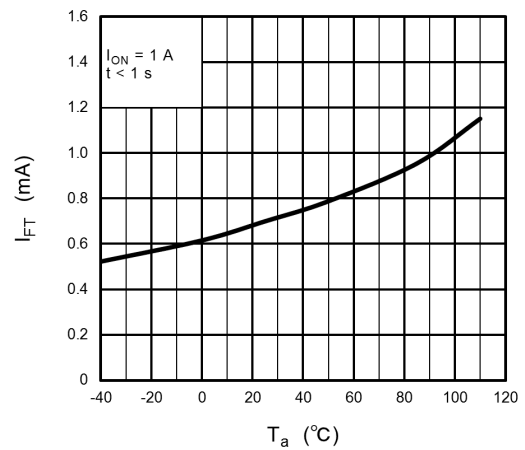


Fig. 12.6 $I_{FT} - T_a$

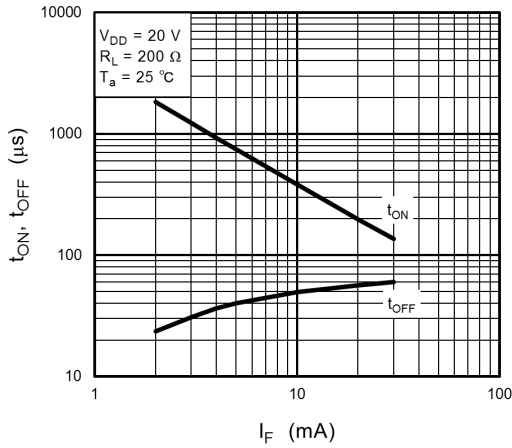


Fig. 12.7 tON, tOFF - I_F

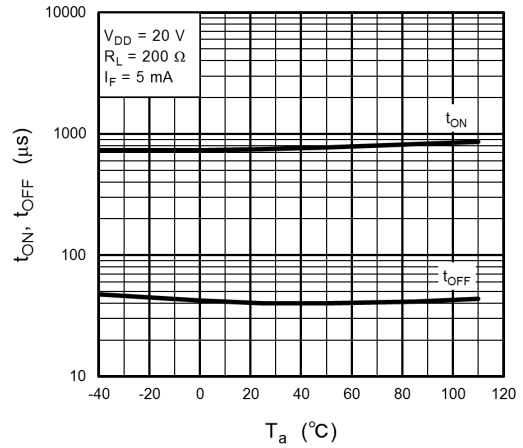


Fig. 12.8 tON, tOFF - T_a

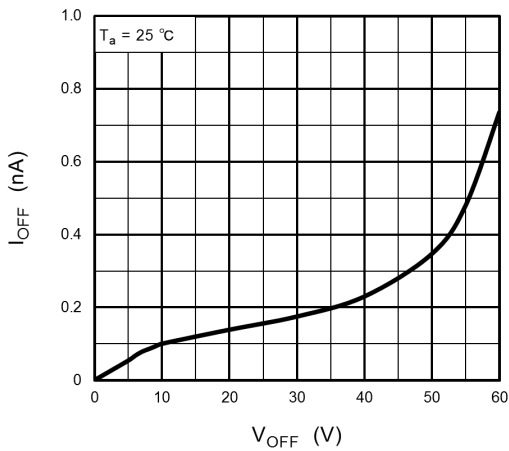


Fig. 12.9 IOFF - VOFF

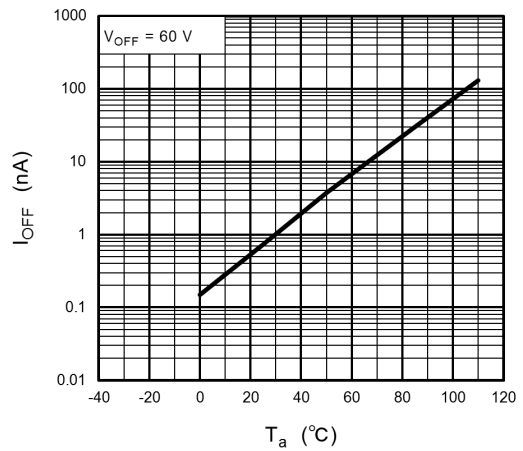


Fig. 12.10 IOFF - T_a

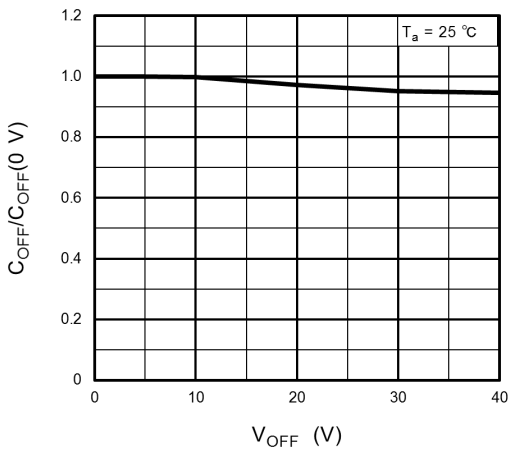


Fig. 12.11 COFF - VOFF

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below.

- When using soldering reflow

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering may be performed up to twice.

The first reflow soldering should be performed within 168 hours after opening the moisture-proof packaging.

The second reflow soldering must be performed within 168 hours of the first reflow.

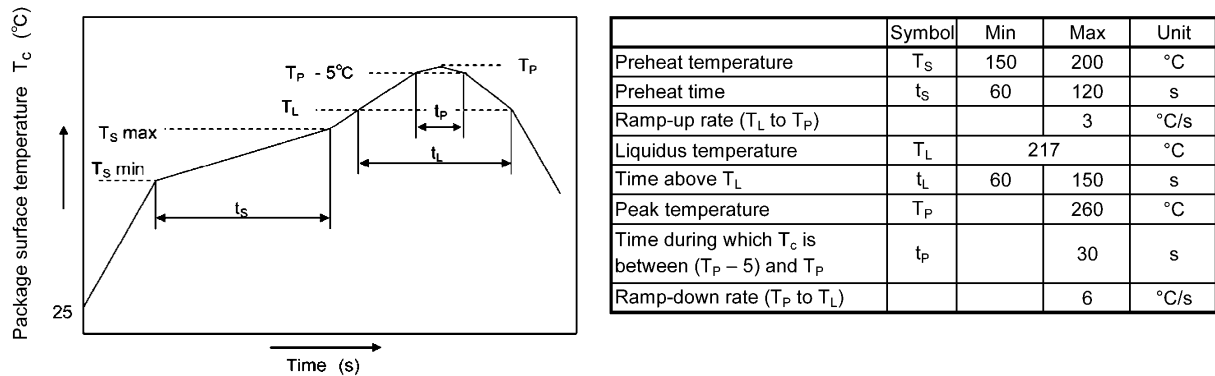
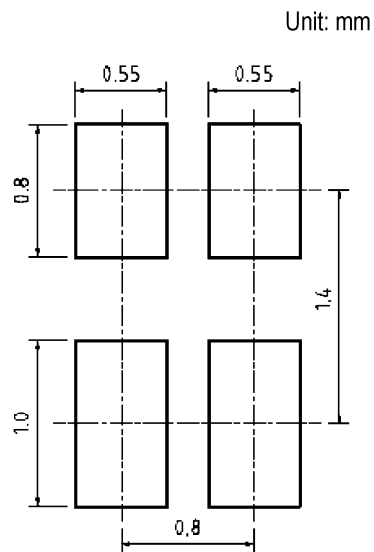
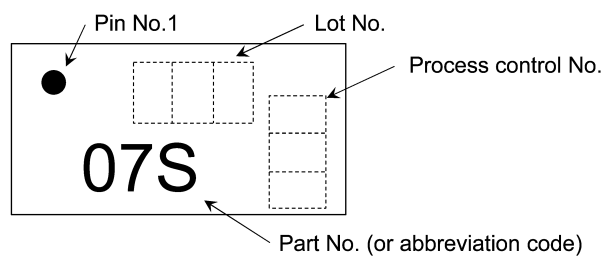


Fig. 13.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Thermal stress may cause a crack in surface-mount products during surface-mount assembly if they have absorbed atmospheric moisture. To prevent a crack, please observe the following precautions.
 1. Moisture-proof bags may be stored unopened for up to 12 months under the following conditions.
 - Temperature: 5 °C to 30 °C
 - Humidity: 90 % (max)
 2. After opening the moisture-proof bag, the devices should be assembled within 168 hours in an environment of 5 °C to 30 °C/70 %RH or below.
 3. If, upon opening, the moisture indicator card shows a humidity of 30 % or above (i.e., has turned pink) or the expiration date has passed, the devices should be baked in tape and reel.
 - After baking, use the baked devices within 72 hours, but perform baking only once.
 - Baking conditions: 60±5 °C, for 64 to 72 hours.
 - Expiration date: 12 months from the sealing date, which is imprinted on the label affixed.
 4. Repeated baking can affect the peeling strength of taping and cause a trouble during mounting.
 - Furthermore, protect the devices against static electricity for baking.
 5. If the laminated packing material is broken, its hermeticity deteriorates. Therefore, do not throw or drop the packed devices.
 6. When restoring devices after removal from their packing, use anti-static containers.

14. Land Pattern Dimensions (for reference only)**15. Marking**

16. Embossed-Tape Packing (TP) Specification for Mini-Flat Photorelays

16.1. Applicable Package

Package Name	Product Type
S-VSON4	Photorelay

16.2. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP3407S(TP,E(O)

Part number: TLP3407S

Tape type: TP

[[G]]/RoHS COMPATIBLE: E (Note 1)

Domestic ID (Country / Region of origin: Japan): (O)

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

16.3. Tape Dimensions Specification

Tape Type	Division	Packing Amount (A unit per reel)
TP	—	2500

16.3.1. Orientation of Device in Relation to Direction of Feed

Device orientation in the carrier cavities as shown in the following figure.

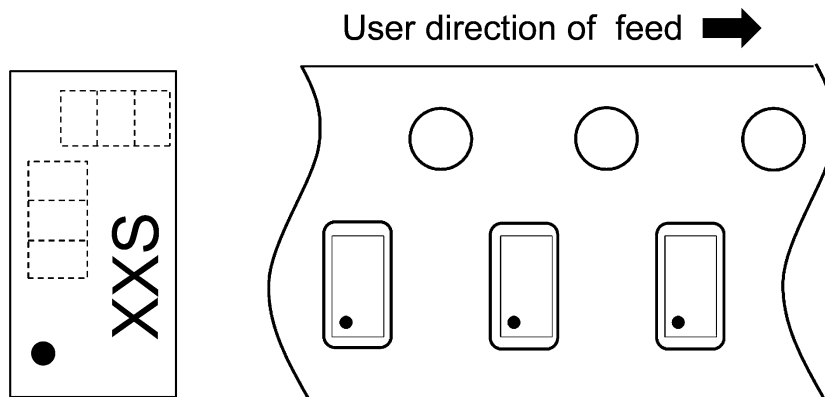


Fig. 16.3.1.1 Device Orientation

16.3.2. Empty Cavities

Characteristics	Criterion	Remarks
Occurrences of 2 or more successive empty cavities	0 device	Within any given 40-mm section of tape, not including leader and trailer
Single empty cavity	6 devices (max) per reel	Not including leader and trailer

16.3.3. Tape Leader and Trailer

The start end of the tape has 40 or more empty cavities. The hub end of the tape has 40 or more empty cavities and one-third empty turn only for a cover tape.

16.3.4. Tape Dimensions

Tape material: Plastic (for protection against static electricity)

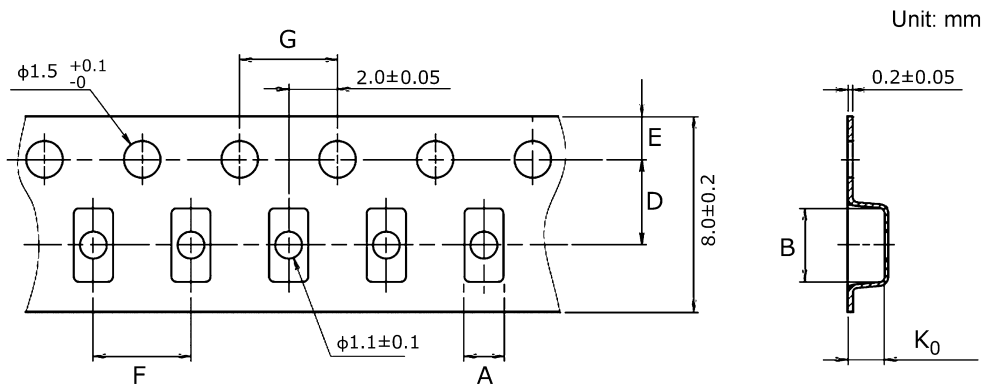


Table Tape Dimensions (unit: mm, tolerance: ±0.1)

Symbol	Dimension	Remark
A	1.6	—
B	2.25	—
D	3.5	Center line of embossed cavity and sprocket hole
E	1.75	Distance between tape edge and sprocket hole center
F	4.0	Cumulative error +0.1/-0.3 (max) per 10 empty cavities holes
G	4.0	Cumulative error +0.1/-0.3 (max) per 10 sprocket holes
K ₀	1.85	Internal space

16.3.5. Reel Specification

Material: Plastic (for protection against static electricity)

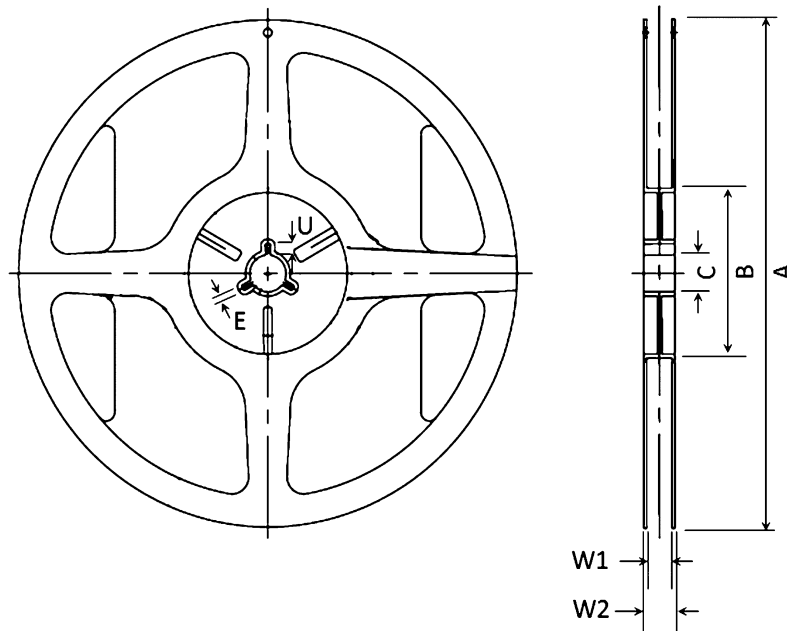


Table Reel Dimensions (unit: mm)

Symbol	Dimension
A	$\phi 180 \pm 3$
B	$\phi 60 \pm 1$
C	$\phi 13 \pm 0.5$
E	2.0 ± 0.5
U	4.0 ± 0.5
W1	9.0 ± 0.3
W2	11.4 ± 1.0

16.4. Packing (Note)

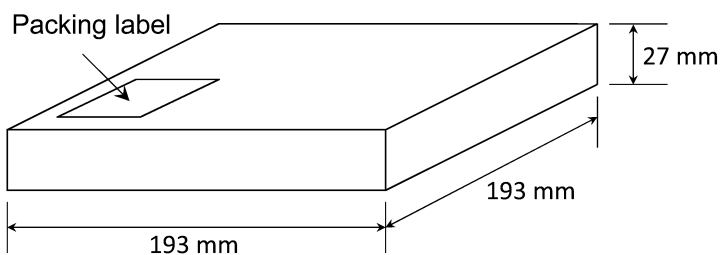


Fig. 16.4.1 1 reel/carton (unit: mm)

Note: Taping reel diameter: $\phi 180$ mm

16.5. Label Format

The carton bears a label indicating the product number, the symbol representing classification of standard, the quantity, the lot number and the Toshiba company name.

16.6. Ordering Information

When placing an order, please specify the part number, tape type and quantity as shown in the following example.

Example) TLP3407S(TP,E(O 2500 pcs

Part number: TLP3407S

Tape type: TP

[[G]]/RoHS COMPATIBLE: E (**Note 1**)

Quantity (must be a multiple of 2500): 2500 pcs

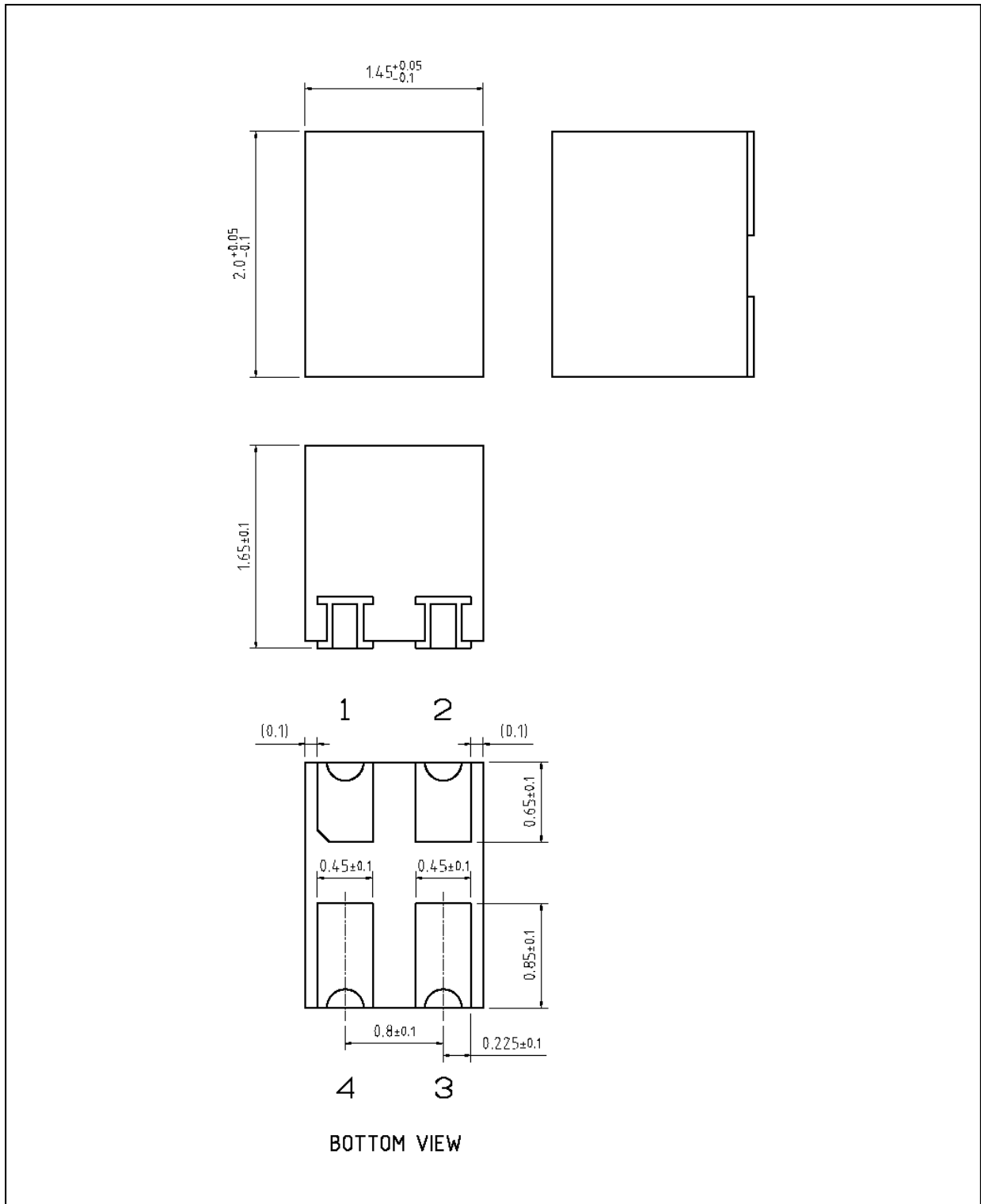
Domestic ID (Country / Region of origin: Japan): (O

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RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Package Dimensions

Unit: mm



Weight: 0.01 g (typ.)

Package Name(s)
TOSHIBA: 11-2E1A

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